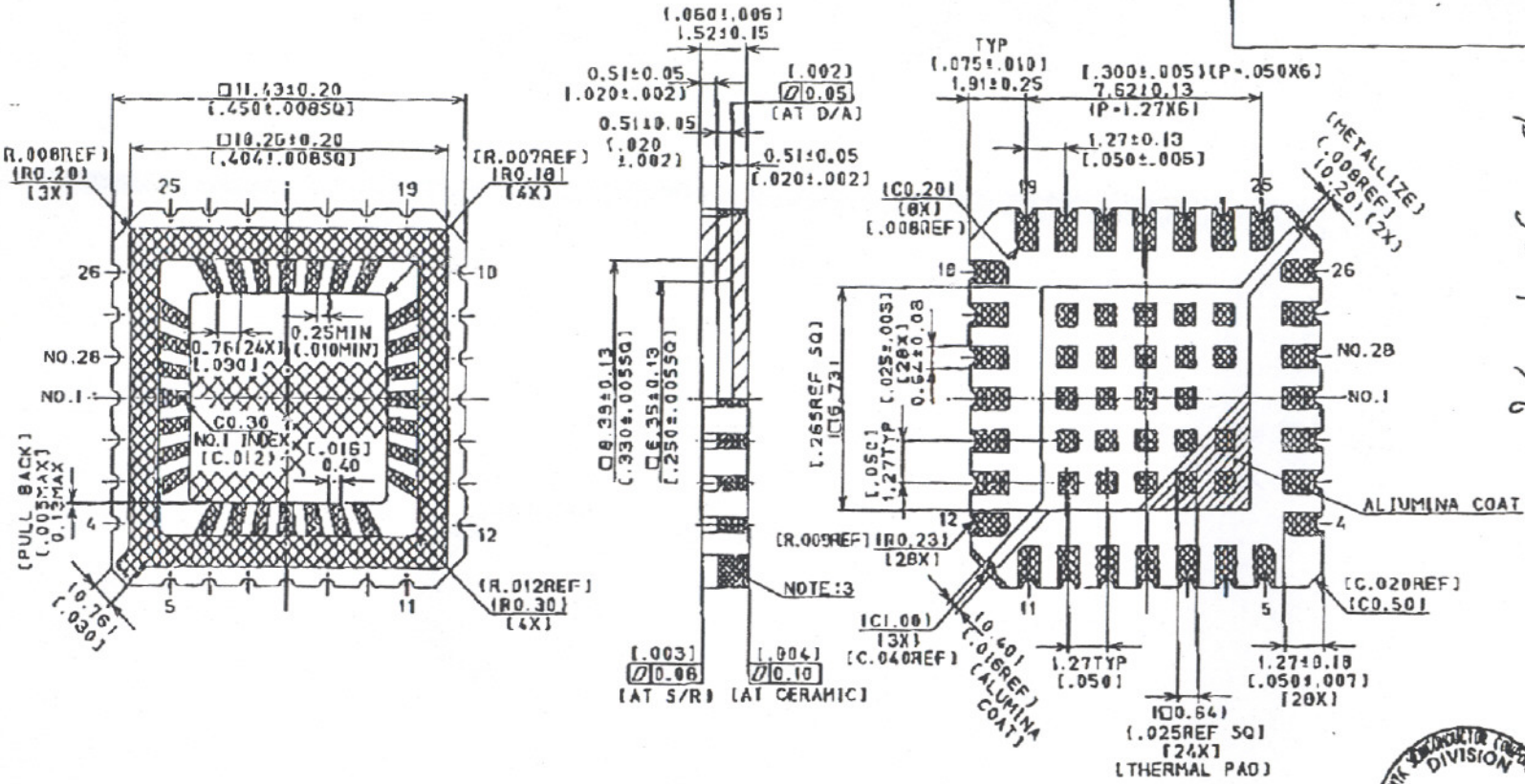
NTK TECHNICAL CERAMICS

LATEST REVISION'S	DESCRIPTION
B	CORRECT THERMAL PAD DESIGN.



B0-3607 2/6

NOTES: 1. GOLD PLATE 1.5μm(60μ") MIN OVER 1.27~8.89μm(50~350μ") NICKEL.

2. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. THERMAL PAD TO BE ISOLATED FROM ANY LEADS. SEAL RING ISOLATED.

3. CORNER METALLIZATION(2X) ARE ELECTRICALLY CONNECTED THERMAL PADS.

NTK SEMICONDUCTOR COMPONENTS DIVISION '02.2.05 NGK SPARK PLUG CO.,LTD.

3				B	RE DRAWING	FEB-1-2002
2				A	RE DRAWING	JAN-2-2001
1	CERAMIC	BLACK ALUMINA		0	NEW DRAWING	JAN-2-2000
Rev.	Name	Material	Description	Rev.	Description	Date

UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1 X N.T.±0.13 (N. L. T. ± MCIVALS. IN L-01 ± MCIVALS. IN L-005)	DRAWN K.HANAI / CHECKED S.MAEHARA / APPROVED J.WASHINO	NTK TECHNICAL CERAMICS NGK SPARK PLUG CO., LTD.
CUSTOMER DEL SEA TECHNOLOGY	DWG NO. MMIHCII	TITLE 28 LEAD CHIP CARRIER
DWG NO. 78-8044-2762-0	SCALE /	DWG NO. 1RK28F1-6910A

MODIFIED DWG NO.

PART NO.

SHEET 1 OF 1